WHAT IS CLAIMED IS:

1. A lamination ceramic chip inductor, formed by the process comprising the steps of:

interposing at least one conductive pattern between at least one pair of insulation layers so as to be in contact with at least one of the pair of insulation layers; and

forming a conductive coil,

wherein the interposing step includes electroforming at least one conductive pattern, and the conductive pattern has a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

2. A lamination ceramic chip inductor according to claim 1, wherein the step of interposing at least one conductive pattern includes interposing a plurality of conductive patterns, and wherein the step further comprises printing a thick film conductor to electrically connect at least two of the conductive patterns to each other.

3. A lamination ceramic chip inductor according to claim 2, wherein the interposing step includes interposing an electroformed conductive pattern having a shape of a straight line.

4. A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes interposing at least one conductive pattern between at least one pair of insulation layers which are magnetic.

5. A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes interposing at least one conductive pattern between insulation layers formed of

claim 8, wherein at least one pair of insulation layers are magnetic.

12. A lamination ceramic chip inductor, comprising at least one conductive pattern formed by an electroforming process using a photoresist, the lamination ceramic chip inductor having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

13. A lamination ceramic chip inductor, according to claim 12, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

14. A lamination ceramic chip inductor, according to claim 13, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

15. A lamination ceramic chip inductor, according to claim 12, wherein at least one pair of insulation layers are magnetic.

a material containing one of a non-shrinkage powder which does not shrink from sintering and a low ratio shrinkage powder which shrinks slightly from sintering.

6. A lamination ceramic chip inductor according to claim 5, wherein the interposing step includes interposing at least one conductive pattern between insulation layers formed of a magnetic material containing an organolead compound as an additive for restricting deterioration of a magnetic characteristic of the insulation layers.

7. A lamination ceramic chip inductor according to claim 1, wherein the interposing step includes electroforming the conductive pattern of a silver plating liquid containing no cyanide.

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8. A lamination ceramic chip inductor, comprising at least one conductive pattern, the lamination ceramic chip inductor having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

9. A lamination ceramic chip inductor, according to claim 8, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

10. A lamination ceramic chip inductor, according to claim 9, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

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11. A lamination ceramic chip inductor, according to

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